# MOSFET - N-Channel, SUPREMOS, FRFET

**600 V, 48.5 A, 65 m** $\Omega$ 

# FCH47N60NF

## **Description**

The SUPREMOS® MOSFET is ON Semiconductor's next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest Rsp on-resistance, superior switching performance and ruggedness. SUPREMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SUPREMOS FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.

#### **Features**

- $650 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ.  $R_{DS(on)} = 57.5 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 240 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 420 pF)
- 100% Avalanche Tested
- This Device is Pb-Free and is RoHS Compliant

#### **Applications**

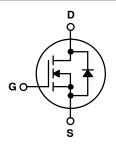
- Solar Inverter
- AC-DC Power Supply



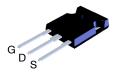
#### ON Semiconductor®

#### www.onsemi.com

V <sub>DS</sub>	V <sub>DS</sub> R <sub>DS(ON)</sub> MAX	
600 V	65 mΩ @ 10 V	48.5 A



**N-CHANNEL MOSFET** 



**TO-247-3LD CASE 340CK** 

#### **MARKING DIAGRAM**



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code

&3 = Numeric Date Code &K = Lot Code

FCH47N60NF = Specific Device Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

## **MOSFET MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Symbol		Parameter	FCH47N60NF	Unit
$V_{DSS}$	Drain to Source Voltage		600	V
$V_{GSS}$	Gate to Source Voltage		±30	V
I <sub>D</sub>	Drain Current	− Continuous (T <sub>C</sub> = 25°C)	45.8	Α
		− Continuous (T <sub>C</sub> = 100°C)	28.9	
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	137.4	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note	2926	mJ	
I <sub>AR</sub>	Avalanche Current (Note 1)		15.3	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		3.7	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		50	
$P_{D}$	Power Dissipation	(T <sub>C</sub> = 25°C)	368	W
		– Derate above 25°C	2.94	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to + 150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Second		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2.  $I_{AS} = 15.3 \text{ A}$ ,  $R_{G} = 25 \Omega$ , starting  $T_{J} = 25 ^{\circ}\text{C}$ 3.  $I_{SD} \le 45.8 \text{ A}$ ,  $di/dt \le 1200 \text{ A}/\mu\text{s}$ ,  $V_{DD} \le 380 \text{ V}$ , starting  $T_{J} = 25 ^{\circ}\text{C}$ 

#### THERMAL CHARACTERISTICS

Symbol	Parameter	FCH47N60NF	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.34	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Package Method	Reel Size	Tape Width	Quantity
FCH47N60NF	FCH47N60NF	TO-247-3LD	Tube	N/A	N/A	30 Units

# **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
OFF CHARA	ACTERISTICS					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 1 mA, V <sub>GS</sub> = 0 V, T <sub>C</sub> = 25°C	600	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, Referenced to 25°C	-	0.78	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V	_	-	10	μΑ
		V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V, T <sub>C</sub> = 125°C	_	-	100	
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	-	±100	nA
ON CHARA	CTERISTICS					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	3	-	5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 23.5 A	-	57.5	65.0	mΩ
9FS	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 23.5 A	-	52	100	S
DYNAMIC C	HARACTERISTICS		•	•		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V,	-	4600	6120	pF
C <sub>oss</sub>	Output Capacitance	f = 1 MHz	_	195	260	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1	_	3.0	5.0	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 380 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	108	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 380 V, V <sub>GS</sub> = 0 V	-	492	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	V <sub>DS</sub> = 380 V, I <sub>D</sub> = 23.5 A,	_	121	157	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V (Note 4)	_	23	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	1`	_	47	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	-	0.9	-	Ω
SWITCHING	CHARACTERISTICS		•	•		
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 380 \text{ V}, I_D = 23.5 \text{ A},$	_	34	78	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 4.7 \Omega$ (Note 4)	_	22	54	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	1	_	117	244	ns
t <sub>f</sub>	Turn-Off Fall Time	1	_	4	18	ns
DRAIN-SOU	RCE DIODE CHARACTERISTICS			•	<u> </u>	
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	47	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	141	Α
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 23.5 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 23.5 A,	-	169	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl <sub>F</sub> /dt = 100 A/μs		1.3	-	μС
	rametric performance is indicated in the Electrical Characteristics for the listed test of		1000	·	·	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially Independent of Operating Temperature Typical Characteristics.

#### **TYPICAL CHARACTERISTICS**

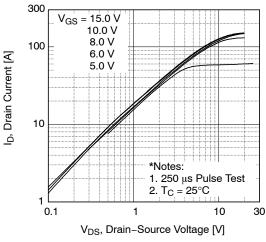


Figure 1. On-Region Characteristics

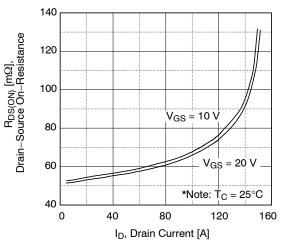


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

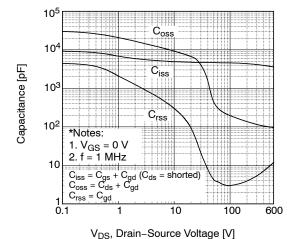


Figure 5. Capacitance Characteristics

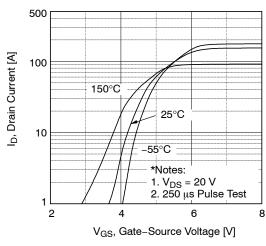


Figure 2. Transfer Characteristics

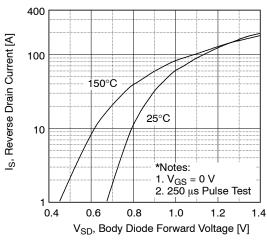


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

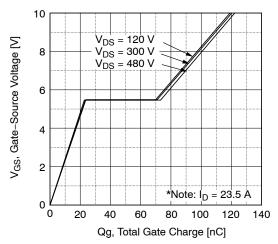


Figure 6. Gate Charge Characteristics

## TYPICAL CHARACTERISTICS (continued)

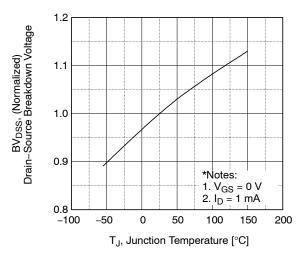


Figure 7. Breakdown Voltage Variation vs. Temperature

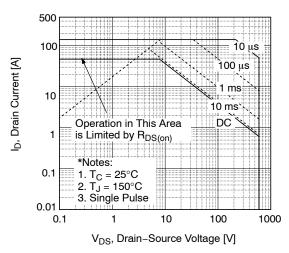


Figure 9. Maximum Safe Operating Area

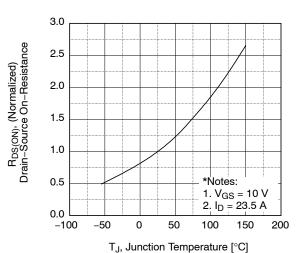


Figure 8. On–Resistance Variation vs. Temperature

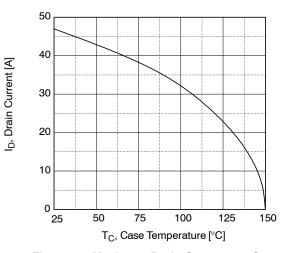


Figure 10. Maximum Drain Current vs. Case Temperature

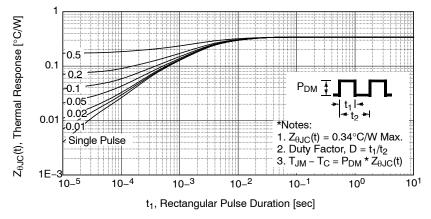


Figure 11. Transient Thermal Response Curve

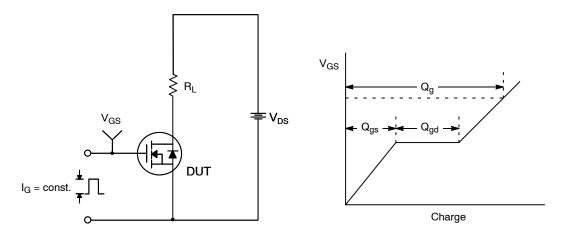


Figure 12. Gate Charge Test Circuit & Waveform

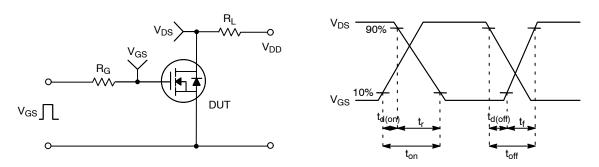


Figure 13. Resistive Switching Test Circuit & Waveforms

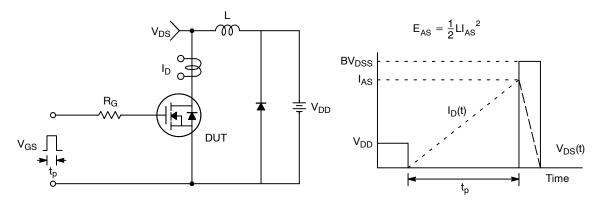


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

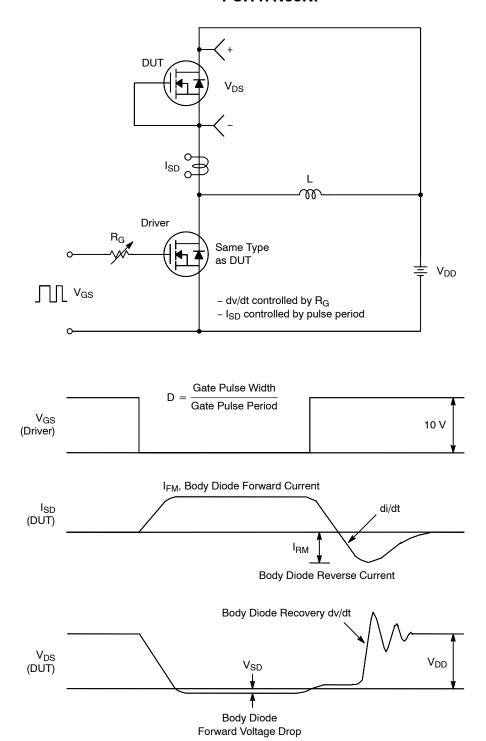


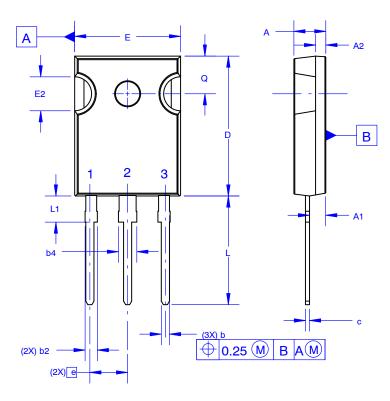
Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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## TO-247-3LD SHORT LEAD

CASE 340CK ISSUE A





- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

# GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code

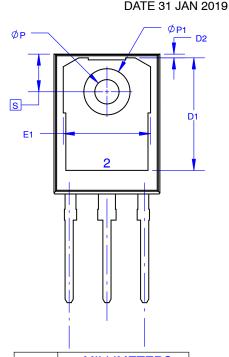
A = Assembly Location

Y = Year

WW = Work Week

ZZ = Assembly Lot Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



DIM	MILLIMETERS				
DIIVI	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D	20.32	20.57	20.82		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E	15.37	15.62	15.87		
E1	12.81	~	~		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	15.75	16.00	16.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
ØP1	6.60	6.80	7.00		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		

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DESCRIPTION:	TO-247-3LD SHORT LEAD		PAGE 1 OF 1	

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